

In th Specification

Please change the title to "Silicon Carbide Contact For Semiconductor Components".

On page 2, line 1, add the following:

--Cross Reference To Related Applications

This application is a continuation of Serial No. 10/351,742, filed 01/27/2003, which is a continuation of Serial No. 09/480,027, filed 01/10/2000, Patent No. 6,563,215 B1.

This application is related to Serial No. 10/187,915, filed 07/01/2002.--

On page 29, lines 14-22, please substitute the following replacement paragraph having the underlined addition.

--In addition to establishing electrical communication with the interconnect 10W, the spring loaded electrical connectors 94 also provide a mechanical force necessary for biasing the interconnect 10W against the component 24W. Further details of a wafer level system similar to the system 86W are contained in U.S. Patent Application No. 08/797,719, filed February 10, 1997, now U.S. Patent No. 6,060,891, entitled "Probe Card For Semiconductor Wafers and Method and System For Testing Wafers" which is incorporated herein by reference.--